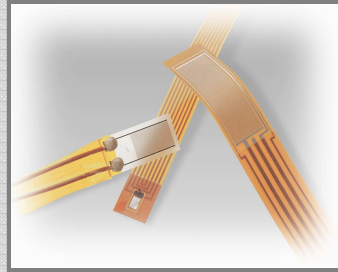


Press Release



- How high is the thermal conductivity of the electronic component?
- Is the chip underfiller sufficiently cured?
- At what temperature does the lead-free solder melt?

The Analyzing & Testing Business Unit at NETZSCH can answer these and similar questions in the fields of thermal analysis and thermophysical properties testing. At the Productronica 2007 in Munich, state-of-the-art instrument techniques tailored to the electronic industry will be presented:

DSC 200 **F3 Maia**[®] with automatic sample changer for measurements of glass transition, melting, crystallization, reaction, specific heat and oxidation stability.

DEA 230/231 **Epsilon** with different sensor types for measuring the curing behavior of various reactive resins, adhesives and coatings – also on-line.

LFA 447 **NanoFlash**[®] for the determination of thermal conductivity – also for multi-layer and anisotropic components.

Come to visit us in hall B5 at the joint booth No. 161 hosted by Bayern Innovativ; we will be pleased to talk with you about your requirements for applications in product development, quality assurance, failure analysis and process optimization!

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